

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau(43) International Publication Date
16 October 2003 (16.10.2003)

PCT

(10) International Publication Number
WO 03/085697 A2(51) International Patent Classification⁷:

H01L

(81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(21) International Application Number: PCT/US03/10149

(22) International Filing Date: 1 April 2003 (01.04.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/369,413 1 April 2002 (01.04.2002) US

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(84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.



WO 03/085697 A2

(54) Title: SOLDER-BEARING ARTICLES AND METHOD OF RETAINING A SOLDER MASS THEREON

(57) Abstract: A method of retaining a solder mass to a solder-bearing article is provided and includes the steps of: (a) forming a plurality of openings in the solder-bearing article; (b) disposing a length of solder mass over at least some of the plurality of openings; and forming a plurality of solder rivets along the length of the solder mass. The solder rivets serve to retain the length of solder mass to the solder-bearing article. The solder-bearing article includes any number of different types of components where a solder mass is held thereby, e.g., leads, terminals, connectors, electromagnetic shields, etc.